

L2	2	I1 and (silver or ag).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:27
L3	11	I1 and (silver or ag).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:27
L4	12575	(silver or ag) near10 (solder or past)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:27
L5	401	(silver or ag) near10 (prevent or preventing or prevented or prevention or penetrate or penetrating or penetrated or penetration) near10 (solder or past)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:28
L6	245	(silver or ag) near5 (prevent or preventing or prevented or prevention or penetrate or penetrating or penetrated or penetration) near5 (solder or past)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:28
L7	9	(silver or ag) near5 (prevent or preventing or prevented or prevention or penetrate or penetrating or penetrated or penetration) near5 (solder or past) and (led or (light adj emitting) adj (diode or device))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:28
L8	9	((silver or ag) near5 (prevent or preventing or prevented or prevention or penetrate or penetrating or penetrated or penetration) near5 (solder or past)) and (led or (light adj emitting) adj (diode or device))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:31
L9	0	((silver or ag) near5 (prevent or preventing or prevented or prevention or penetrate or penetrating or penetrated or penetration) near5 (solder or past)).clm. and (led or (light adj emitting) adj (diode or device))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:31

L10	0	((silver or ag) near5 (prevent or preventing or prevented or prevention or penetrate or penetrating or penetrated or penetration) near5 (solder or paste)).clm. and (led or (light adj emitting) adj (diode or device))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:31
L11	8	((silver or ag) near5 (prevent or preventing or prevented or prevention or penetrate or penetrating or penetrated or penetration) near5 (solder or paste)).ti,ab,clm. and (led or (light adj emitting) adj (diode or device))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:33
L12	885	package and (silver or ag) and (led or (light adj emitting adj (device or diode))) and (pcb or (printed adj circuit adj boar) or board)'and (solder or paste)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:34
L13	35	package and (silver or ag) and (led or (light adj emitting adj (device or diode))) and (pcb or (printed adj circuit adj boar) or board) and (solder or paste) and ((silver or ag) near10 (solder or soldering or paste)).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:34
L14	17	package.ti,ab,clm. and (silver or ag) and (led or (light adj emitting adj (device or diode))) and (pcb or (printed adj circuit adj boar) or board) and (solder or paste) and ((silver or ag) near10 (solder or soldering or paste)).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:34
L15	17	package.ti,ab,clm. and (silver or ag) and (led or (light adj emitting adj (device or diode))) and (pcb or (printed adj circuit adj board) or board) and (solder or paste) and ((silver or ag) near10 (solder or soldering or paste)).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:34
L16	7	package.ti,ab,clm. and (silver or ag) and (led or (light adj emitting adj (device or diode))) and (pcb or (printed adj circuit adj board) or board).ti,ab,clm. and (solder or paste) and ((silver or ag) near10 (solder or soldering or paste)).ti, ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:35

L17	0	package.ti,ab,clm. and (silver or ag) and (led or (light adj emitting adj (device or diode))) and (pcb or (printed adj circuit adj board) or board).ti,ab,clm. and (solder or paste) and ((silver or ag) near10 (solder or soldering or paste)).ti, ab,clm. and (silver or ag).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:36
L18	26434	((silver or ag) near10 (seal or sealing or adhesive or epoxy or resin))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:37
L19	675	((silver or ag) near10 (seal or sealing or adhesive or epoxy or resin)).ti,ab,clm. and (package or packaging).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:37
L20	222	((silver or ag) near10 (seal or sealing or adhesive or epoxy or resin) near10 (solder or paste or soldering)).ti,ab,clm. and (package or packaging).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:38
L21	4	((silver or ag) near10 (seal or sealing or adhesive or epoxy or resin) near10 (solder or paste or soldering)).ti,ab,clm. and (package or packaging).ti,ab,clm. and (led or (light adj emitting adj (device or diode))).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:39
L22	0	10/707443	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:40
L23	18	(lighthouse adj technology)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:42
L24	13	chang and chih-chin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:42
L25	20	I23 or I24 and (silver or ag)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:43

L26	18	I23 or I24 and (silver or ag) and (solder or soldering or paste or epoxy or resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:43
L27	18	I23 or I24 and (silver or ag).ti,ab,clm. and (solder or soldering or paste or epoxy or resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:43
L28	18	I23 or I24 and (silver or ag).clm. and (solder or soldering or paste or epoxy or resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:43
L29	0	(I23 or I24) and (silver or ag).clm. and (solder or soldering or paste or epoxy or resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:43
L30	31	(I23 or I24)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:43
L31	9	I30 and (silver or ag)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:43
L32	0	I30 and (silver or ag).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:43
L33	0	I30 and (silver or ag).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:44
L34	149	(package or packaging) same (silver or ag) same (solder or soldering or epoxy or resin) same (board or pcb) same (seal or sealing or adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:45
L35	46	((package or packaging) same (silver or ag) same (solder or soldering or epoxy or resin) same (board or pcb) same (seal or sealing or adhesive)) and (silver or ag).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:45

L36	8	((package or packaging) same (silver or ag) same (solder or soldering or epoxy or resin) same (board or pcb) same (seal or sealing or adhesive)) and (silver or ag).ti,ab,clm. and ((solde or ag) near10 (seal or sealing or adhesive) near10 (solder or soldering or epoxy or resin))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 17:46
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